



100% Material Declaration Data Sheet for 7-Series SBV484

PK816(v1.0) November 8, 2016

Average Weight : 1.4867 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die	Silicon	7440-21-3	100.00	basis	0.237468	15.973%
					0.009525	0.641%
Bump	Tin	7440-31-5	98.20	basis	0.009354	
	Silver	7440-22-4	1.80	basis	0.000171	
Underfill					0.034000	2.287%
	Bisphenol F type liquid epoxy	9003-36-5	15.00	basis	0.005100	
	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6	10.00	basis	0.003400	
	Bisphenol A type liquid epoxy	25068-38-6	5.00	basis	0.001700	
	Amine type hardener	trade secret	10.00	basis	0.003400	
	Silicon dioxide	60676-86-0	58.00	filler	0.019720	
	Carbon black	1333-86-4	1.00	color agent	0.000340	
	Additives	trade secret	1.00	additives	0.000340	
Solder ball					0.233980	15.738%
	Tin	7440-31-5	96.50	Main material	0.225791	
	Silver	7440-22-4	3.00	Main material	0.007019	
Substrate	Copper	7440-50-8	0.50	Main material	0.001170	
					0.971727	65.361%
	Copper	7440-50-8	36.37		0.353520	
	Tin	7440-31-5	0.79		0.007677	
	Silver	7440-22-4	0.02		0.000194	
	Core	N/A	46.77		0.454477	
	ABF	N/A	13.8		0.134098	
Solder Mask	N/A	2.24		0.021761		

Revision History

Date	Version	Description of Revisions
11/8/2016	1.0	Initial Xilinx release.